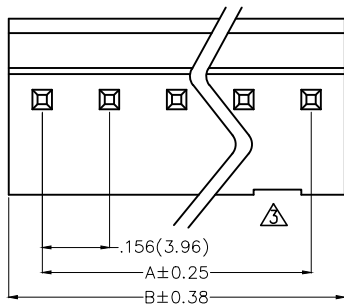


1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Dimension $\phi.065(\phi1.65)$ Change to $\phi.071(1.80)$	20150919	CHERRY	FAN
2	△	Size change	14/MAY/20	KATE	CHERRY
3	△	Structural and size changes	22/APR/21	KATE	JOHNNY
4	△	Flammability Change	09/MAY/24	KATE	LEO

A



B

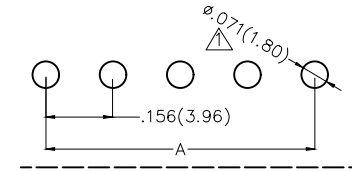
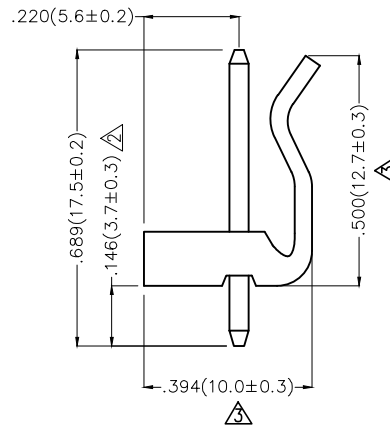
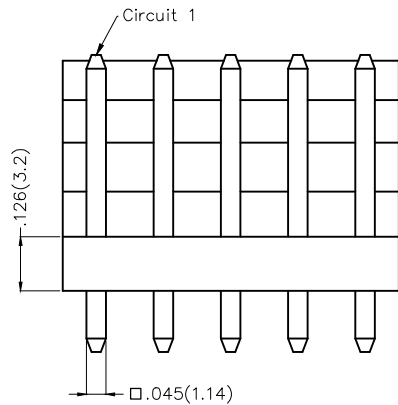
Electrical

Current Rating: 5A AC(rms)/DC
 Voltage Rating: 250V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 1500V AC r.m.s
 Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-2) △
 Contact Pin: Brass
 Plating: Tin Plated

C



Recommended P.C.Board Layout

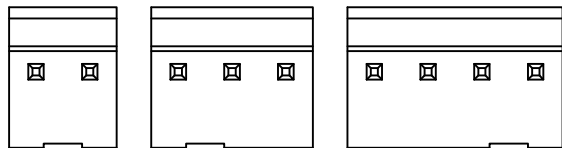
D

Ordering Information

FWF 396 03 — S XX S 2 2 T B
 1 2 3 4 5 6 7 8 9 10

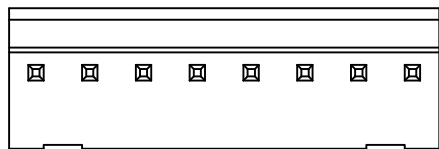
1 Category FWF—Wafer	2 Series Number 396—Pitch 3.96mm	3 Distinction No. 03	4 Row Option S—Single Row	5 Circuits XX	6 Entry Angle S—180° Vertical
7 Plating 2—Tin Plated	8 Material—Resin 2—PA66	9 Color—Resin T—Transparent	10 Packaging B—PE Bag		

E



2 Circuits 3,6,7 Circuits 4,5 Circuits

F



8~12 Circuits

 THIRD ANGLE PROJECTION DESIGN UNITS Inch (metric) SCALE 5:1 SIZE A4	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 19/SEP/15	PART NO. FWF39603—SXXS22TB	ITEM NO. FWF39603	 Leader Of Industry REV 4 SHEET NO. 1/2
	X.±.012(0.30)	X:±5°	CHECKED BY CHERRY	DATE 19/SEP/15	TITLE Wire to Board (Wafer) Pitch 3.96mm 180° Vertical (DIP)		
	X.XX±.008(0.20)	.X:±2°	DRAWN BY JACOB	DATE 19/SEP/15	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	X.XX±.006(0.15)	.XX±1°					
		X.XXX±.004(0.10)	.XXX±0.5°				

1 2 3 4 5 6 7 8

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

B

C

D

E

F

A

B



C

D

E

F

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF39603-S02S22TB	.156(3.96)	.311(7.92)
3	FWF39603-S03S22TB	.311(7.92)	.468(11.88)
4	FWF39603-S04S22TB	.468(11.88)	.624(15.84)
5	FWF39603-S05S22TB	.624(15.84)	.780(19.80)
6	FWF39603-S06S22TB	.780(19.80)	.935(23.76)
7	FWF39603-S07S22TB	.935(23.76)	1.091(27.72)
8	FWF39603-S08S22TB	1.091(27.72)	1.247(31.68)
9	FWF39603-S09S22TB	1.247(31.68)	1.403(35.64)
10	FWF39603-S10S22TB	1.403(35.64)	1.559(39.60)
11	FWF39603-S11S22TB	1.559(39.60)	1.715(43.56)
12	FWF39603-S12S22TB	1.715(43.56)	1.871(47.52)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 19/SEP/15	PART NO. FWF39603-SXXS22TB	ITEM NO. FWF39603	 Leader Of Industry	
	X.±.012(0.30)	X'.±5'	CHECKED BY CHERRY	DATE 19/SEP/15	TITLE Wire to Board (Wafer) Pitch 3.96mm 180° Vertical (DIP)			REV 4
	DESIGN UNITS Inch (metric)	X.XX±.008(0.20)	.X'±2'	DRAWN BY JACOB	DATE 19/SEP/15	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX'±1'	X.XXX±.004(0.10)	.XXX'±0.5'		

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8